Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	210	134/58	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/26 15:00
L2	5	yang adj reg.in.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/26 14:59
L3	849	134/56R	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/26 15:01
L4	94	134/89	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/26 15:01
L5	174552	(wafer or substrate or semi\$1conductor or semiconductor or plate) and (rotat\$3 or spin\$3 or spinning or turn\$4) and (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) with (side or perpendicular or lateral or horizontal\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2007/10/26 15:17
L6	109858	(wafer or substrate or semi\$1conductor or semiconductor or plate) same (rotat\$3 or spin\$3 or spinning or turn\$4) and (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) with (side or perpendicular or lateral or horizontal\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2007/10/26 15:18
L7	9885	(wafer or substrate or semi\$1conductor or semi\$1conductor or semiconductor or plate) same (rotat\$3 or spin\$3 or spinning or turn\$4) and clean\$3 same (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) with (side or perpendicular or lateral or horizontal\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2007/10/26 15:23
L8	0	kingpak adj technology adj inc.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2007/10/26 15:21
L9	1100	(wafer or substrate or semi\$1conductor or semiconductor). ab. same (rotat\$3 or spin\$3 or spinning or turn\$4) and (clean\$3 or wash\$3 or rins\$3) with (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) same (side or perpendicular or lateral or horizontal\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2007/10/26 15:24

L10 781 (wafer or substrate or semi\$1conductor or semiconductor). ab. same (rotat\$3 or spin\$3 or spinning or turn\$4) and (clean\$3 or wash\$3 or rins\$3) with (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) same (side or perpendicular or lateral or horizontal\$3) and (wafer or substrate or semi\$1conductor or semiconductor) with (support\$3 or hold\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2007/10/26 15:25
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Ref	Hits	Search Query	DBs	Default	Plurals	Time Stamp
#				Operator		
L1	43	(wafer or substrate or semi\$1conductor or semiconductor). ab. same (rotat\$3 or spin\$3 or spinning or turn\$4) and (clean\$3 or wash\$3 or rins\$3) with (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) with (side or perpendicular or lateral or horizontal\$3) and (wafer or substrate or semi\$1conductor or semiconductor) same (support\$3 or hold\$3) and sealed and (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) with (nitrogen or "N.2" or n2 or (carbon adj dioxide) or co2 or "co.2")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2007/10/26 17:20
L2	0	(wafer or substrate or semi\$1conductor or semiconductor). ab. same (rotat\$3 or spin\$3 or spinning or turn\$4) and (clean\$3 or wash\$3 or rins\$3) with (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) with (side or perpendicular or lateral or horizontal\$3) and (wafer or substrate or semi\$1conductor or semiconductor) same (support\$3 or hold\$3) and sealed and (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) with (nitrogen or "N.2" or n2 or (carbon adj dioxide) or co2 or "co.2") and interference adj fit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2007/10/26 17:14
L3	0	(wafer or substrate or semi\$1conductor or semiconductor). ab. same (rotat\$3 or spin\$3 or spinning or turn\$4) and (clean\$3 or wash\$3 or rins\$3) with (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) with (side or perpendicular or lateral or horizontal\$3) and (wafer or substrate or semi\$1conductor or semiconductor) same (support\$3 or hold\$3) and interference adj fit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2007/10/26 17:16
L4	11	(wafer or substrate or semi\$1conductor or semiconductor). ab. same (rotat\$3 or spin\$3 or spinning or turn\$4) and (clean\$3 or wash\$3 or rins\$3) with (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) and (wafer or substrate or semi\$1conductor or semiconductor) same (support\$3 or hold\$3) and interference adj fit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2007/10/26 17:19

L5	36	(wafer or substrate or semi\$1conductor or semiconductor). ab. same (rotat\$3 or spin\$3 or spinning or turn\$4) and (clean\$3 or wash\$3 or rins\$3) with (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) and (wafer or substrate or semi\$1conductor or semiconductor) same (support\$3 or hold\$3) and clip\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2007/10/26 17:20
L6	13	(disc or disk).ab. same (rotat\$3 or spin\$3 or spinning or turn\$4) and (clean\$3 or wash\$3 or rins\$3) with (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) with (side or perpendicular or lateral or horizontal\$3) and (disc or disk) same (support\$3 or hold\$3) and sealed and (nozzle or eject\$3 or spray\$3 or emit\$4 or jet\$4) with (nitrogen or "N.2" or n2 or (carbon adj dioxide) or co2 or "co.2")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2007/10/26 17:34